

Connector Datasheet

PT06J0000BY8

RJ45 1×2 Tab Down W/LED W/O Spring
W/1000 Base-T Transformer

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TECHNICAL INFORMATION

1 SCOPE

1.1 Content

1.1.1 This specification covers performance, tests and quality requirements for RJ45 1×2 Tab Down W/LED W/O Spring W/1000 Base-T Transformer

2 APPLICABLE DOCUMENTS

The following documents form a part of this specification to the extent specified herein.

Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

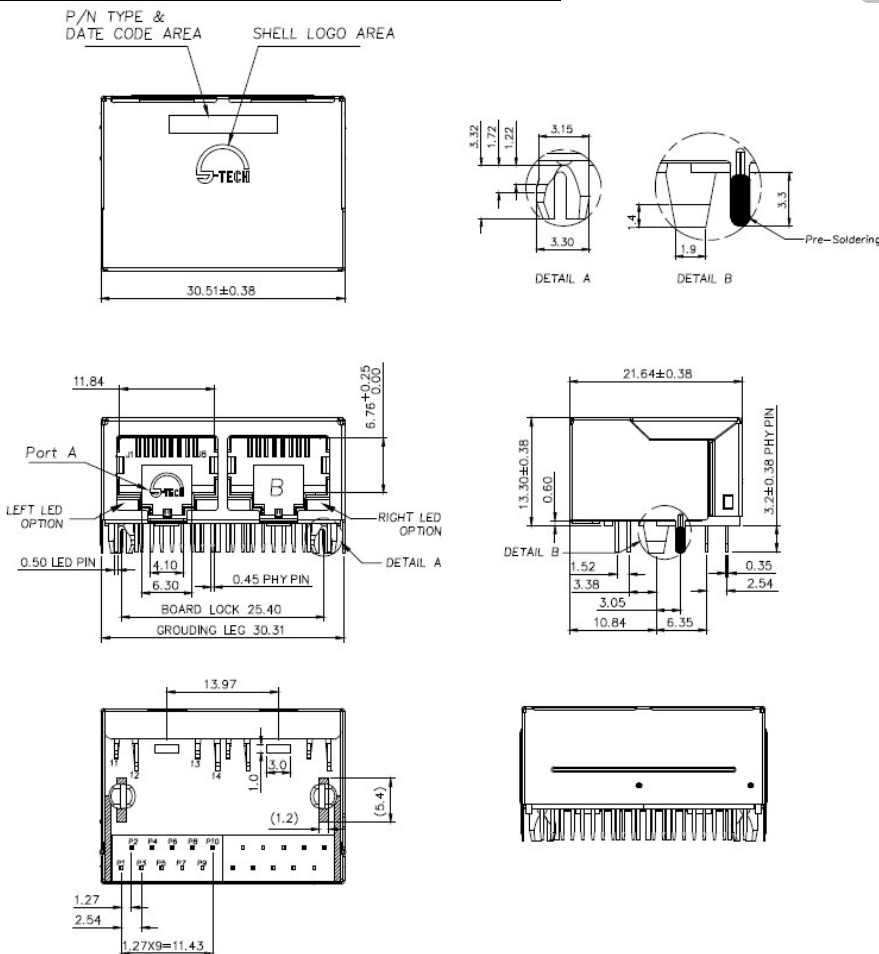
2.1 Commercial standards, specifications and report

2.1.1 MIL-STD-1344A

2.1.2 EIA-364

3 MECHANIC DIMENSIONS

Component Configuration and Dimensions

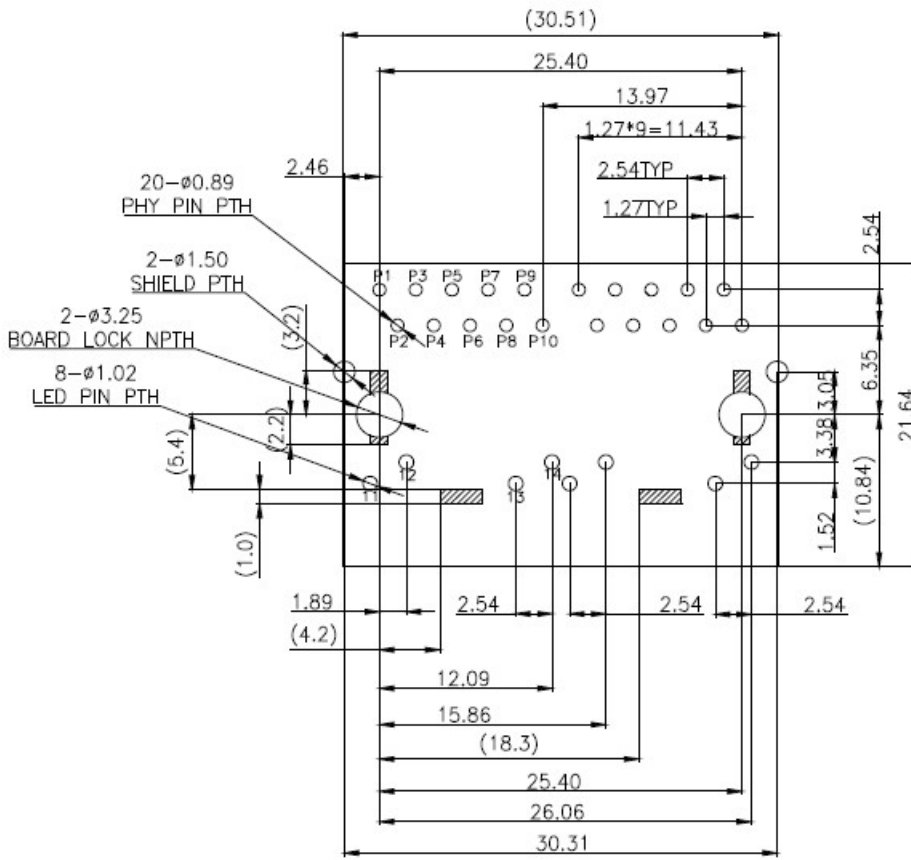


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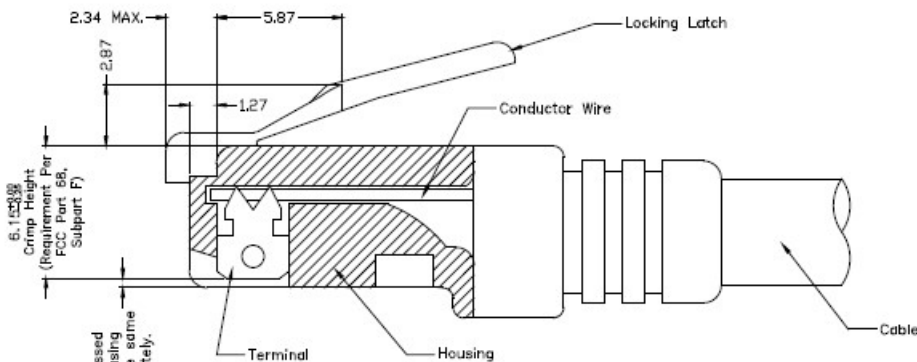
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Pins assignment for PCB Layout



RECOMMENDED PCB LAYOUT
 COMPONENT SIDE
 ALL DIMENSION TOLERANCE ARE $\pm 0.05\text{mm}$
 UNLESS OTHERWISE SPECIFIED

4 Recommended Modular Plug



All contacts recessed below top of housing and must be at the same height approximately.

There must be no damage to housing or locking latch.
 There must be no nicks or cuts in cable.

STANDARD MODULAR PLUG ASSEMBLY

5 REQUIREMENTS

5.1 Design and Construction

5.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.

5.2 Materials and Finish

5.2.1 Contact:

5.2.1.1 RJ Contact : Phosphor Bronze

Finish : (a) Contact Area : 30 μ " Au Min

(c) Solder tail Area : 100 μ " Min Matted Tin

(c) Underplating : 50 μ " Min Nickel over all

5.2.1.2 Joint Contact : Phosphor Bronze

Finish : 100 μ " Matted Tin & 50 μ " Min Nickel over all

5.2.2 Plastic Part:

5.2.2.1 Housing: High temperature engineering Plastic, Yellow 114C

Flame Class: UL94 V-0

5.2.2.2 Module: High temperature engineering Plastic, Black

Flame Class: UL94 V-0

5.2.3 Shell

5.2.3.1 Shell: Stainless steel

5.2.3.2 Shell of Grounding Pin: Pre-soldering Sn

5.3 LED Lamp

Emitting color	λ p(nm)	Vf@If= 20mA	Ir@Vr=5V
Green	565	1.7-2.6	10 uA max
Yellow	585	1.7-2.6	10 uA max

5.4 Operating and Storage Temperature

5.4.1 Operating Temperature : 0°C TO +70°C

5.4.2 Storage Temperature : -40°C TO +85°C

5.5 Ratings

5.5.1 Voltage rating : 150 VAC Maximum

5.5.2 Current rating : 1.5 A Maximum

5.5.3 Contact Resistance: 30m Ω

5.5.4 Insulation Resistance: 500 Meagohms Minimum

5.6 Mechanical Characteristics

5.6.1 Mating force: 20N MAX

5.6.2 Unmating force (w/o tab locking): 20N MAX

5.6.3 Durability: 1000 cycles

5.7 Reliability Test:

5.7.1 Resistance to soldering heat - High Temperature Resistance:

265 \pm 5/-0°C , 3-5 seconds for 2 times.

5.7.2 Rework temperature: 350°C Max. 3~5seconds for 3 times.

5.8 Environmental Test:

5.8.1 Moisture Resistance : MSL level-3

5.8.2 Saving life: 1 year

5.8.3 Thermal shock cycle Test: Expose Sample connectors under the temperature changes between -40°C and 85°C for 25 cycles holding for 30minutes at the both extremes, in accordance with test method of SPEC.

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5.8.4 Temperature life: Subject Sample connectors to temperature life at 85°C for 168hours. EIA-364-22B, Class shell be satisfied.

5.8.5 Humidity test: Subject Sample connector, to relative humidity 85%RH and a temperature of 85°C for 168 hours. It shall be subjected to standard atmospheric. Class shell be satisfied. MIL-STD-1344A.method:1002.2.

5.9 Performance and Test Description

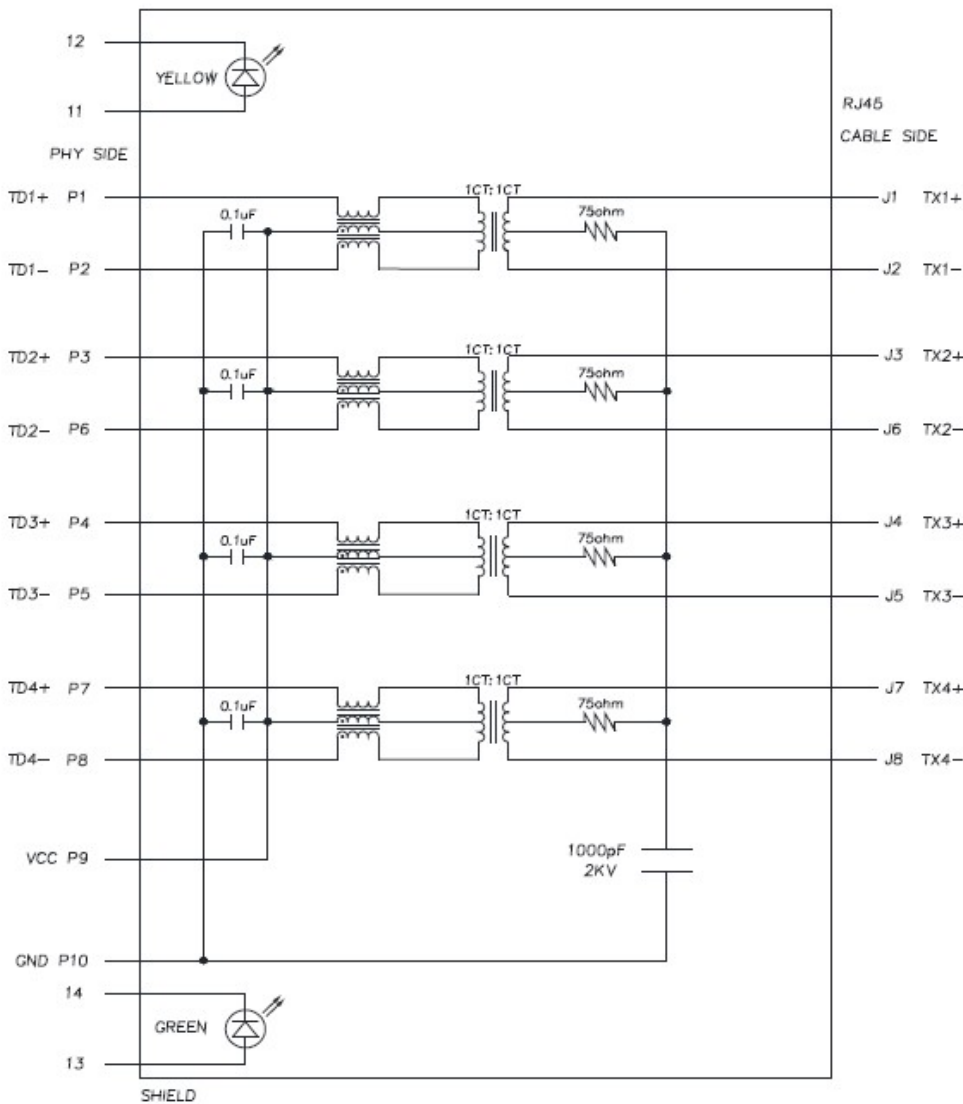
Product is designed to meet electrical, mechanical and environmental performance requirements. All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

5.10 Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

6 ELECTRICAL CHARACTERISTICS

6.1 Schematic



6.2 Insertion loss :

- 1-100 MHz - 1.0dB MAX.
- 100~125 MHz - 1.2dB MAX.
- Return loss : 1-30 MHz - 18dB MIN. load 100 Ω
- 30-60 MHz - 16dB MIN. load 100 Ω
- 60-80 MHz - 12dB MIN. load 100 Ω
- 80~100 MHz - 10dB MIN. load 100 Ω

6.3 Common Mode Rejection

@ 1~100 MHz - 30dB MIN.

6.4 Cross Talk

@ 1~100 MHz - 30dB MIN

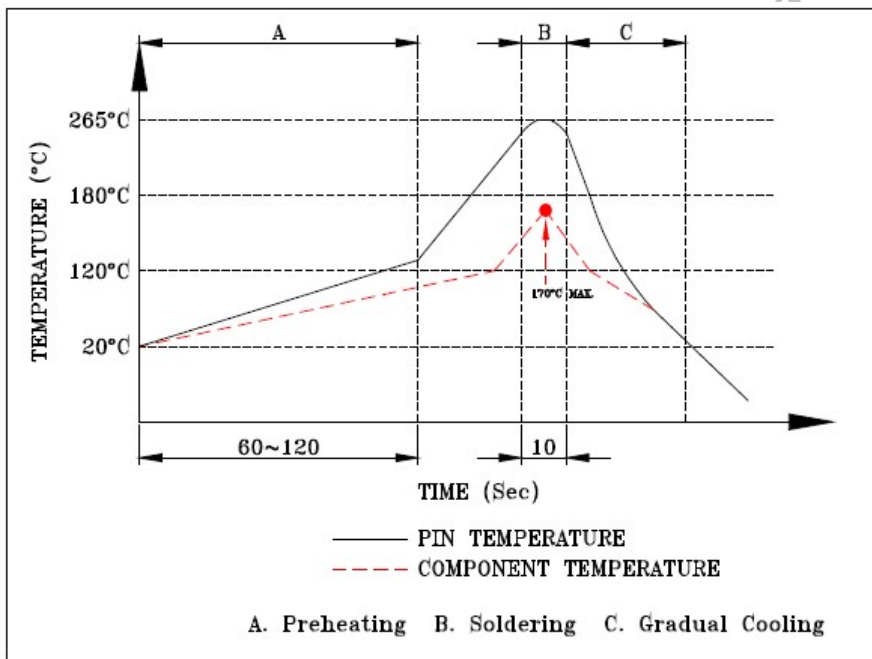
6.5 Primary Inductance

@100KHz, 0.1V, 8mA DC BIAS.
 P (1-2), P(3-6), P(4-5), P(7-8): 350uH MIN.

6.6 Hi-Pot TEST

PRIMARY TO SECONDARY: 2250 VDC.

Resistance to flow solder heat



SUGGESTED WAVE SOLDER CURVE

- (1)Tip temperature : 265+5/-0°C
- (2)Tip temperature time : 3~5sec

Note: The product specification only for standard product